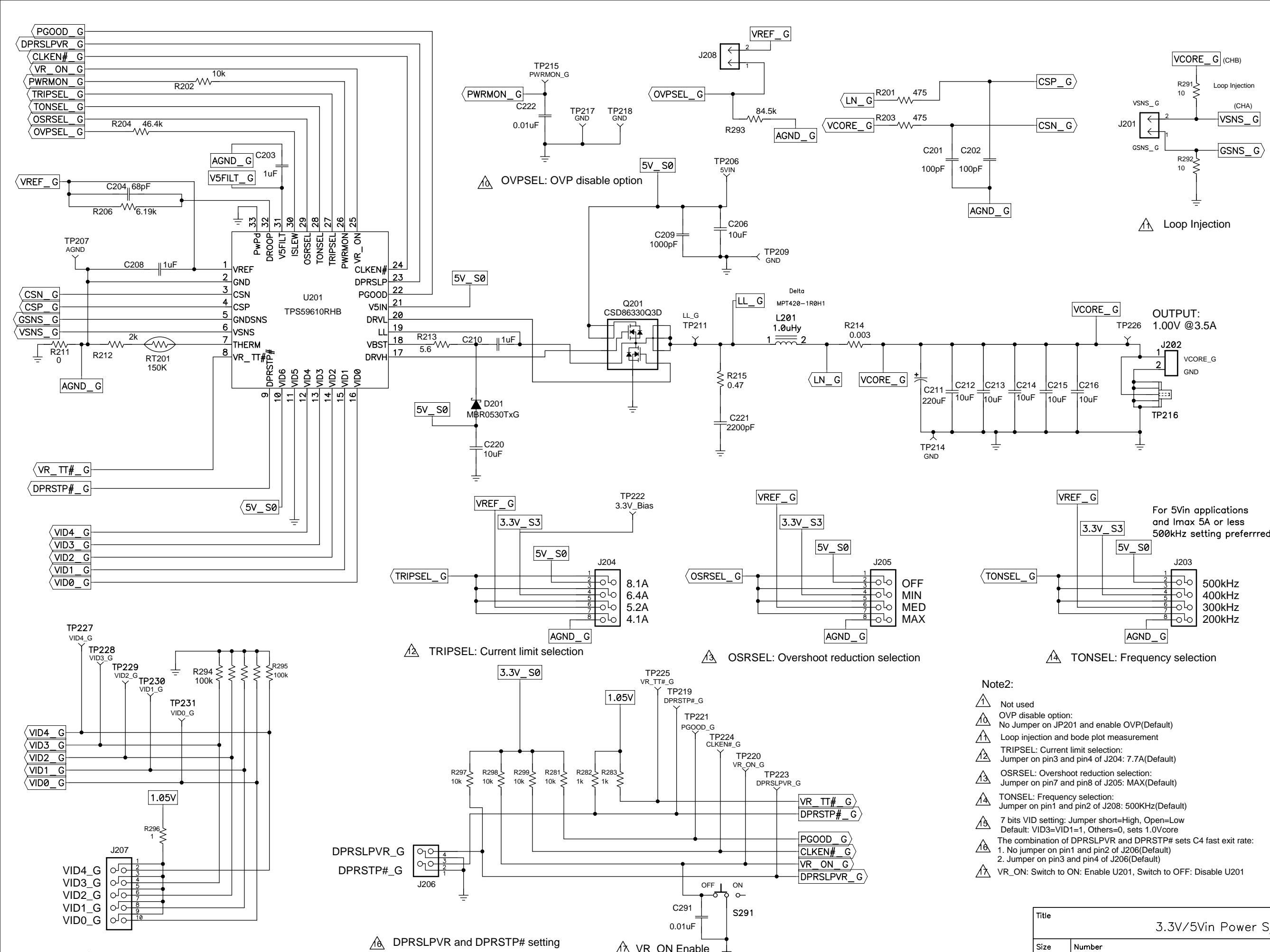


- Note 1:**
- 1 Not used
 - 2 OVP disable option:
No Jumper on JP101 and enable OVP(Default)
 - 3 Loop injection and bode plot measurement
 - 4 TRIPSEL: Current limit selection:
Jumper on pin3 and pin4 of J104: 7.7A(Default)
 - 5 OSRSEL: Overshoot reduction selection:
Jumper on pin7 and pin8 of J105: MAX(Default)
 - 6 TONSEL: Frequency selection:
Jumper on pin1 and pin2 of J108: 500KHz(Default)
 - 7 7 bits VID setting: Jumper short=High, Open=Low
Default: VID5=1, Others=0, sets 1.10Vcore
 - 8 The combination of DPRSLPVR and DPRSTP# sets C4 fast exit rate:
1. No jumper on pin1 and pin2 of J106(Default)
2. Jumper on pin3 and pin4 of J106(Default)
 - 9 VR_ON: Switch to ON: Enable U101, Switch to OFF: Disable U101

CPU Core

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C19x, R19x, R18x and all connectors / headers are Test Interface Parts

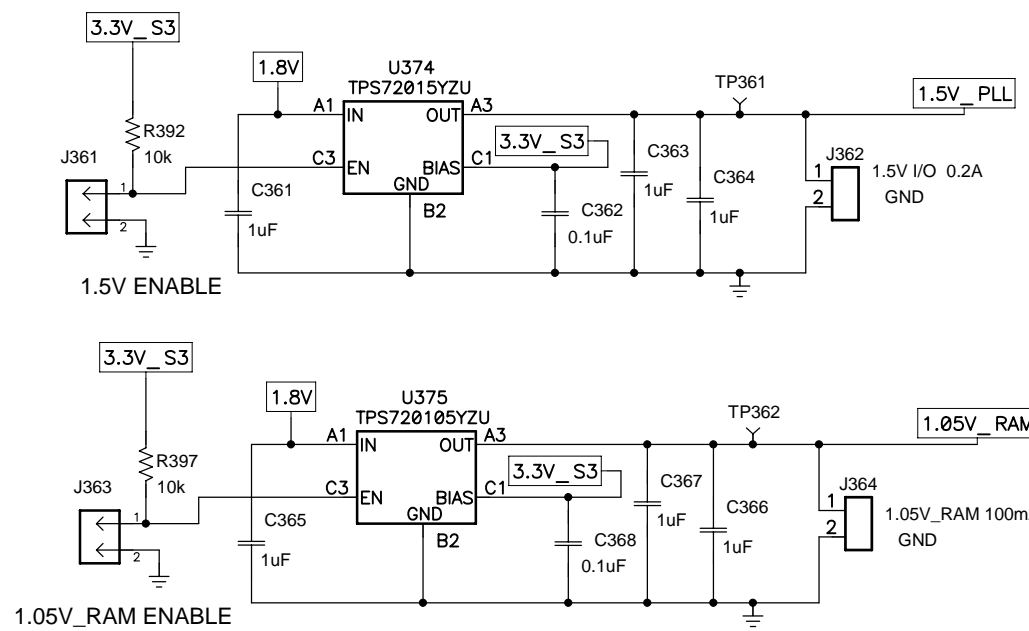
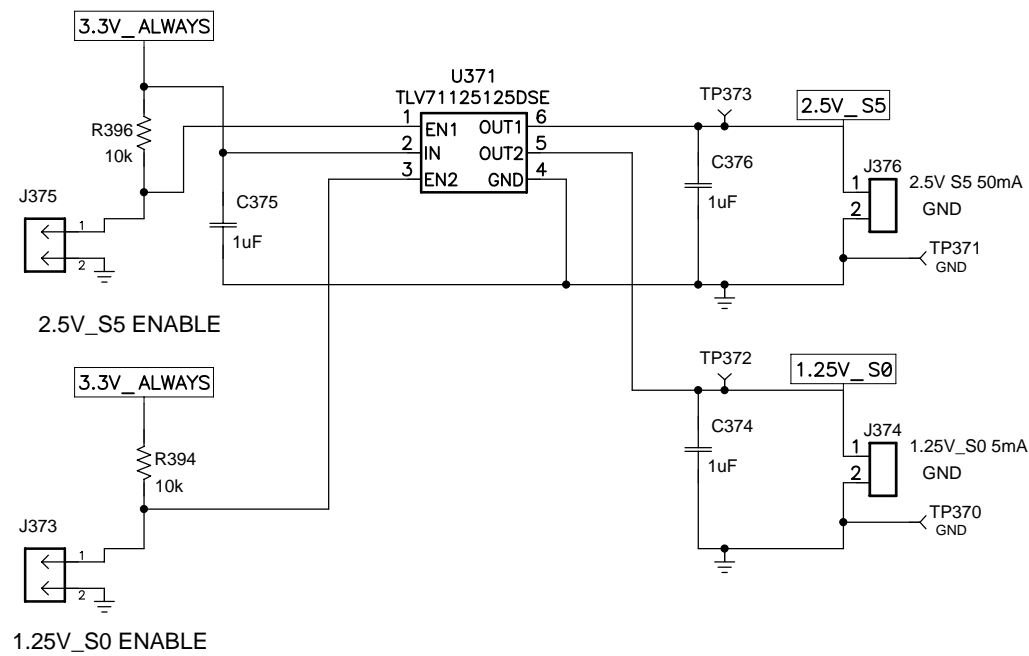
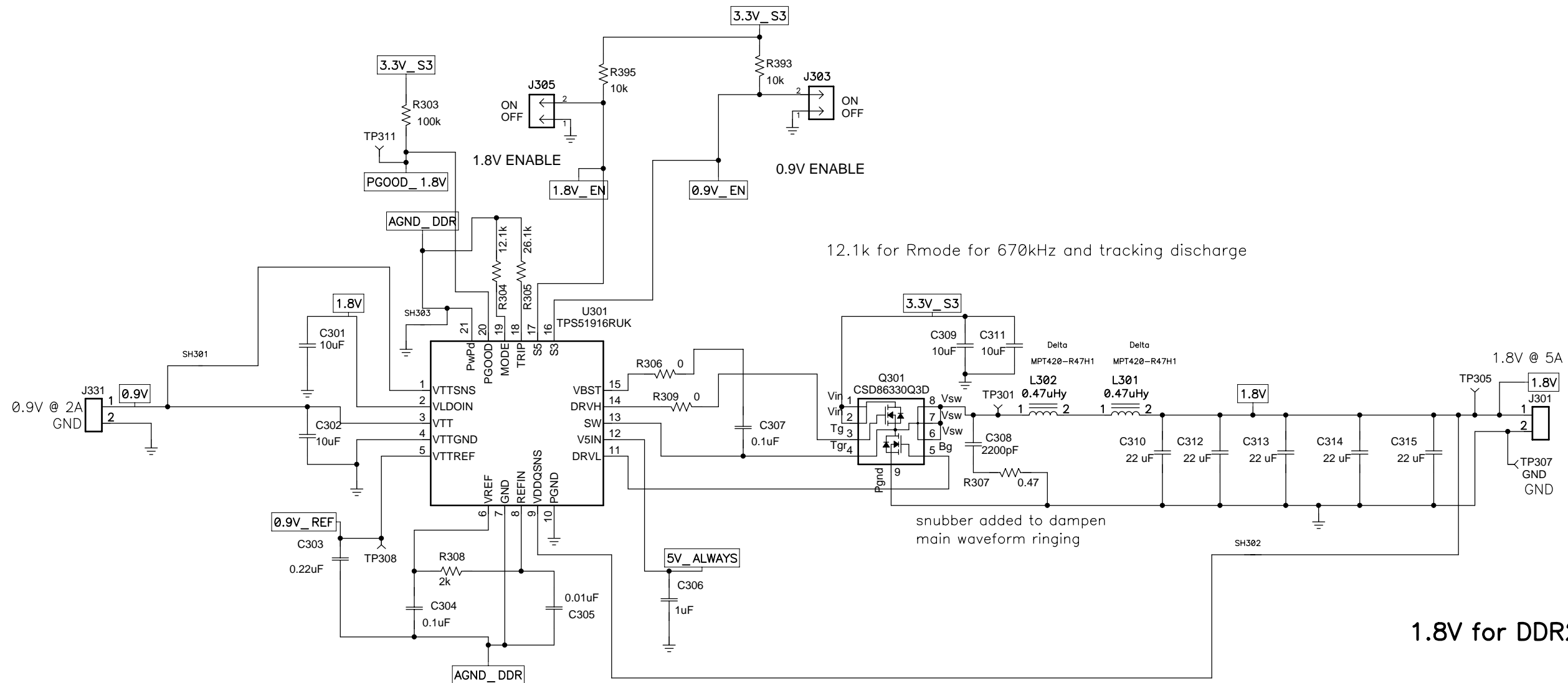


- Note2:**
- ⚠ Not used
 - ⚠ OVP disable option:
No Jumper on JP201 and enable OVP(Default)
 - ⚠ Loop injection and bode plot measurement
 - ⚠ TRIPSEL: Current limit selection:
Jumper on pin3 and pin4 of J204: 7.7A(Default)
 - ⚠ OSRSEL: Overshoot reduction selection:
Jumper on pin7 and pin8 of J205: MAX(Default)
 - ⚠ TONSEL: Frequency selection:
Jumper on pin1 and pin2 of J208: 500KHz(Default)
 - ⚠ 7 bits VID setting: Jumper short=High, Open=Low
Default: VID3=VID1=1, Others=0, sets 1.0Vcore
 - ⚠ The combination of DPRSLPVR and DPRSTP# sets C4 fast exit rate:
1. No jumper on pin1 and pin2 of J206(Default)
2. Jumper on pin3 and pin4 of J206(Default)
 - ⚠ VR_ON: Switch to ON: Enable U201, Switch to OFF: Disable U201

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GPU Core

C29x, R29x, R28x and all connectors / headers are Test Interface Parts

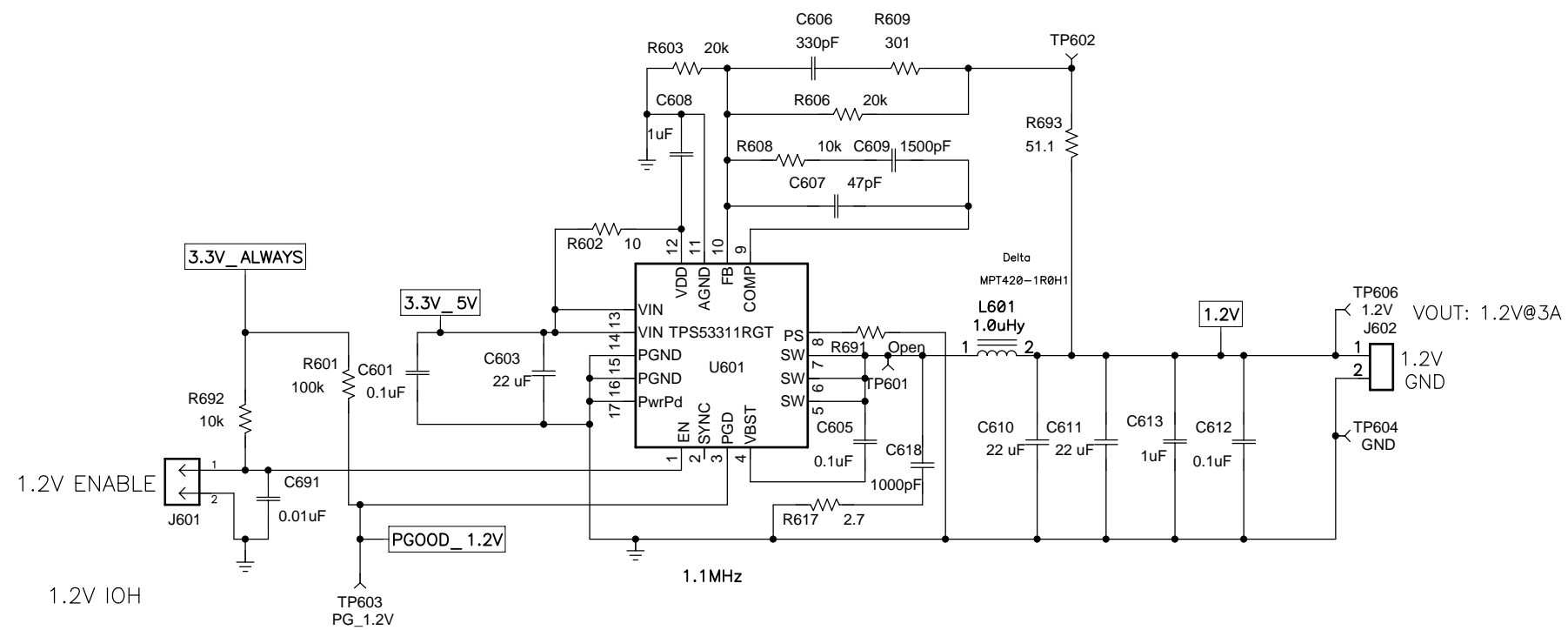
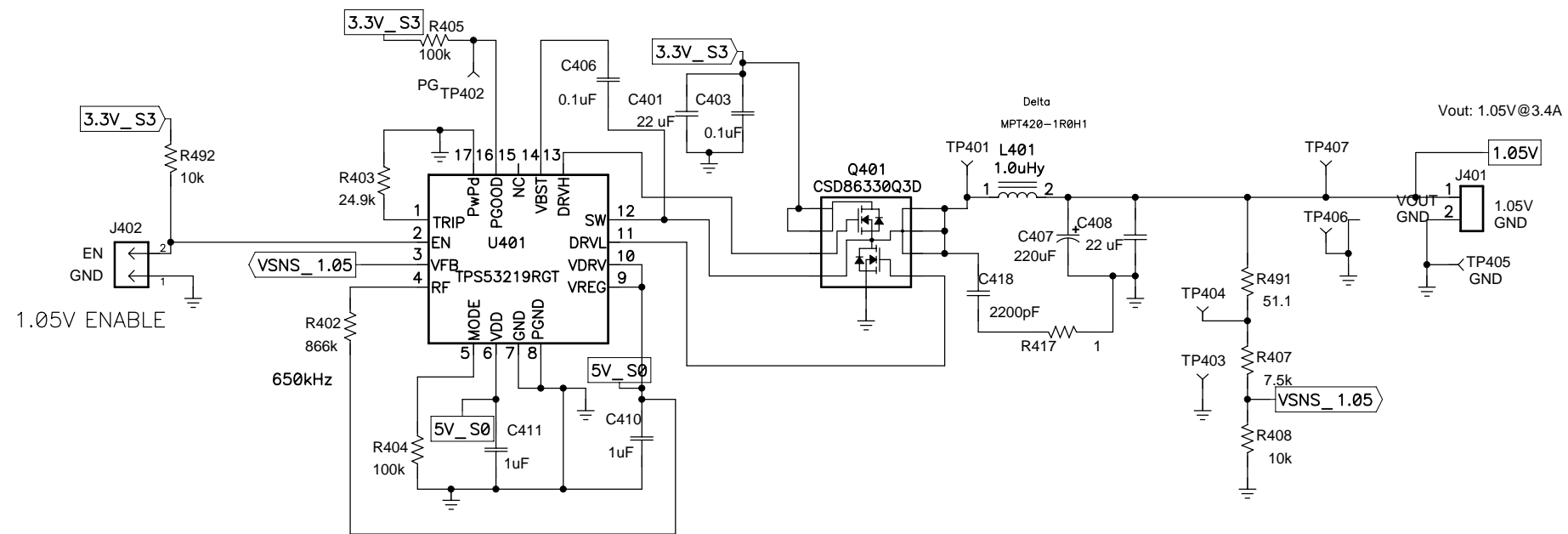


R39x and all connectors / headers are Test Interface Parts

DDR2 & Linars

Title			3.3V/5Vin Power System		
Size	Number	PMP5922		Rev	C
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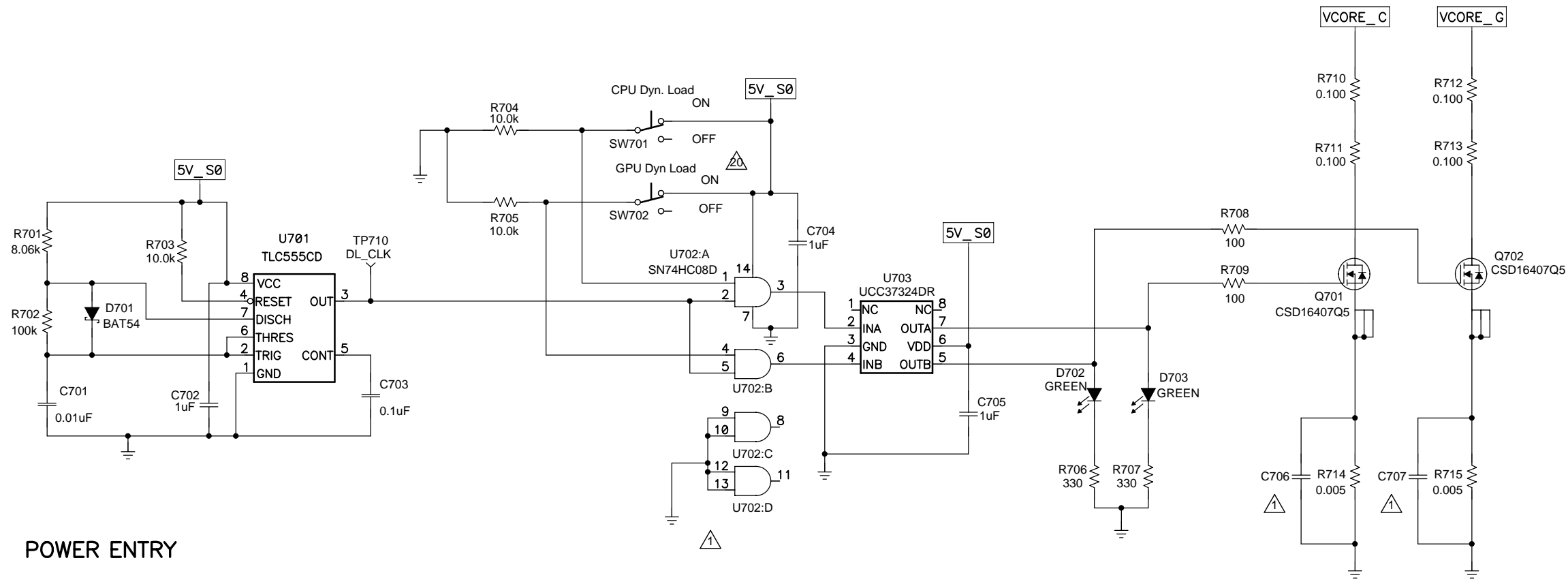
1.05V I/O



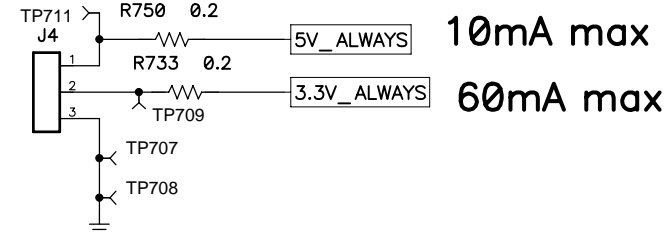
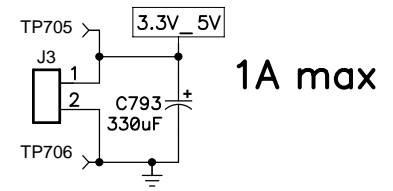
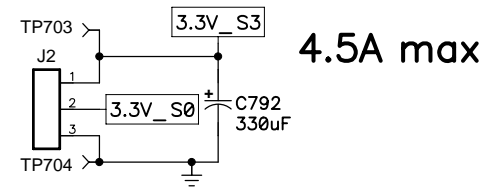
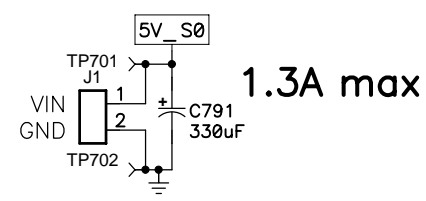
R49x, R69x, C69x and all connectors / headers are Test Interface Parts

1.2V & 1.05V

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POWER ENTRY



All parts on this page are Test Interface Parts

Note4:

- ⚠ Not used
- ⚡ On Board Dynamic Load:
 1. SW701: ON Enable CPU Core Dynamic load
OFF Disable CPU Core Dynamic load
 2. SW702: ON Enable GPU Core Dynamic load
OFF Disable GPU Core Dynamic load

On Board Dynamic Load for CPU, GPU

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